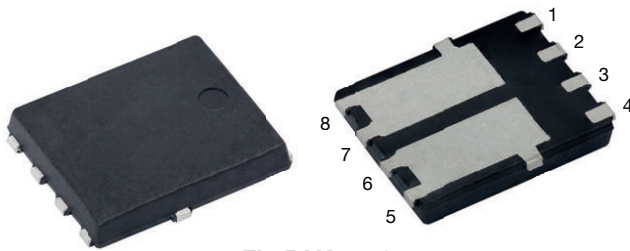
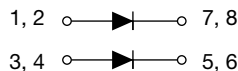


## Hyperfast Rectifier, 2 x 3 A FRED Pt<sup>®</sup>


**FlatPAK 5 x 6**


### LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2 x 3 A
$V_R$	200 V
$V_F$ at $I_F$	0.71 V
$t_{rr}$	25 ns
$T_J$ max.	175 °C
Package	FlatPAK 5 x 6
Circuit configuration	Separated cathode

### FEATURES

- Hyper fast recovery time, reduced  $Q_{rr}$ , and soft recovery
- 175 °C maximum operating junction temperature
- Low forward voltage drop
- Low leakage current
- Specific for output and snubber operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
 COMPLIANT  
 HALOGEN  
**FREE**

### DESCRIPTION / APPLICATIONS

State of the art hyper fast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyper fast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in snubber, boost, lighting, as high frequency rectifiers and freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element.

### MECHANICAL DATA

**Case:** FlatPAK 5 x 6

Molding compound meets UL 94 V-0 flammability rating  
 Halogen-free, RoHS-compliant

**Terminals:** matte tin plated leads, solderable per J-STD-002, meets JESD 201 class 2 whisker test

### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	$V_{RRM}$		200	V
Average rectified forward current per device	$I_{F(AV)}$	$T_{Solderpad} = 170\text{ °C}$ , DC	3	
Non-repetitive peak surge current per device	$I_{FSM}$	$T_{Solderpad} = 169\text{ °C}$ , $D = 0.5$	147	A
per diode		$T_J = 25\text{ °C}$ , 10 ms sinusoidal pulse	70	

### ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}$ , $V_R$	$I_R = 100\text{ }\mu\text{A}$	200	-	-	V
Forward voltage	$V_F$	$I_F = 3\text{ A}$	-	0.88	0.94	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	-	2	$\mu\text{A}$
		$T_J = 150\text{ °C}$ , $V_R = V_R$ rated	-	6	40	
Junction capacitance	$C_T$	$V_R = 200\text{ V}$	-	14	-	pF

<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time	$t_{rr}$	$I_F = 1.0\text{ A}$ , $di_F/dt = 50\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	26	-	ns	
		$I_F = 0.5\text{ A}$ , $I_R = 1\text{ A}$ , $I_{rr} = 0.25\text{ A}$	-	-	25		
		$T_J = 25\text{ }^\circ\text{C}$	-	15	-		
		$T_J = 125\text{ }^\circ\text{C}$	-	25	-		
Peak recovery current	$I_{RRM}$	$I_F = 3\text{ A}$ $di_F/dt = 200\text{ A}/\mu\text{s}$ $V_R = 160\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$	-	2	-	A
			$T_J = 125\text{ }^\circ\text{C}$	-	3	-	
Reverse recovery charge	$Q_{rr}$	$I_F = 3\text{ A}$ $di_F/dt = 200\text{ A}/\mu\text{s}$ $V_R = 160\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$	-	12	-	nC
			$T_J = 125\text{ }^\circ\text{C}$	-	40	-	

<b>THERMAL - MECHANICAL SPECIFICATIONS</b>						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J, T_{Stg}$		-55	-	175	$^\circ\text{C}$
Thermal resistance, junction to ambient	$R_{thJA}$ (1)(2)		-	90	103	
Thermal resistance, junction to mount	$R_{thJM}$ (3)		-	2.3	2.6	$^\circ\text{C}/\text{W}$

**Notes**

- (1) The heat generated must be less than thermal conductivity from junction to ambient;  $dP_D/dT_J < 1 \times R_{thJA}$
- (2) Free air, mounted or recommended copper pad area; thermal resistance  $R_{thJA}$  - junction to ambient
- (3) Mounted on infinite heatsink

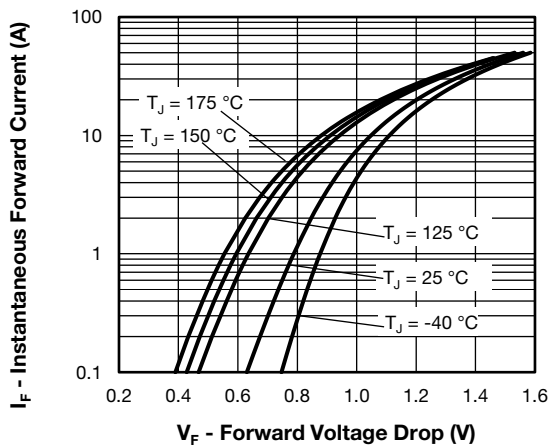


Fig. 1 - Typical Forward Voltage Drop Characteristics

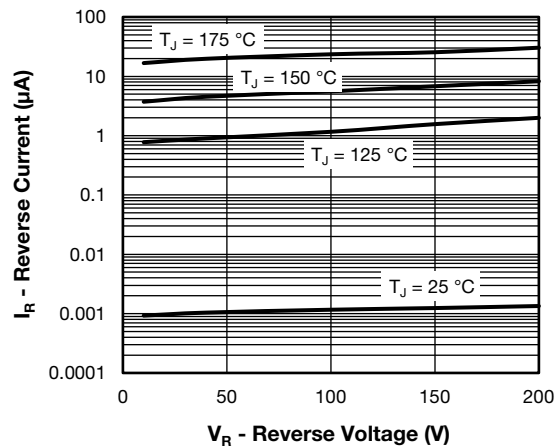


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

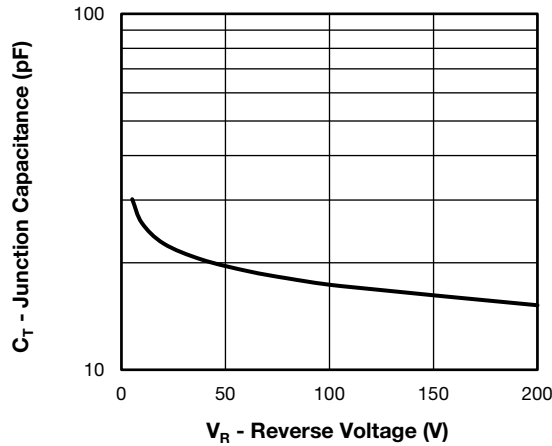


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

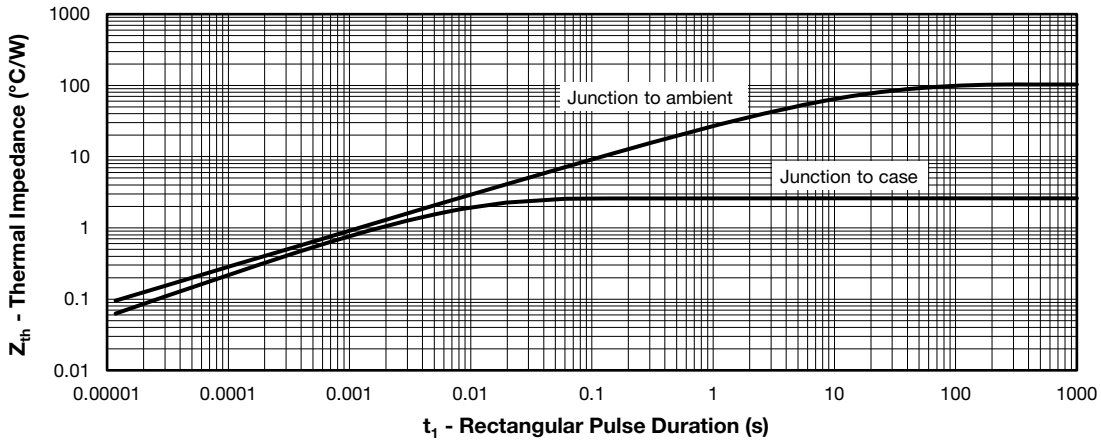


Fig. 4 - Maximum Thermal Impedance  $Z_{th}$  Characteristics

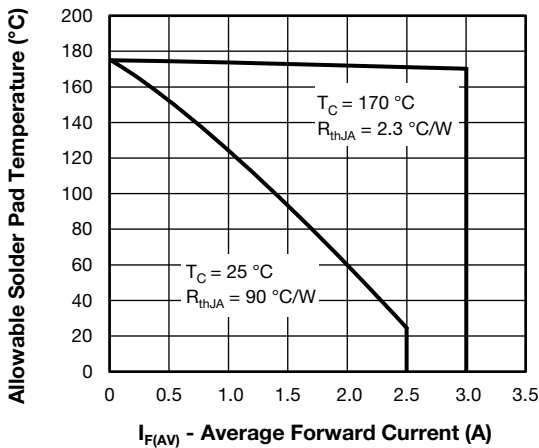


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

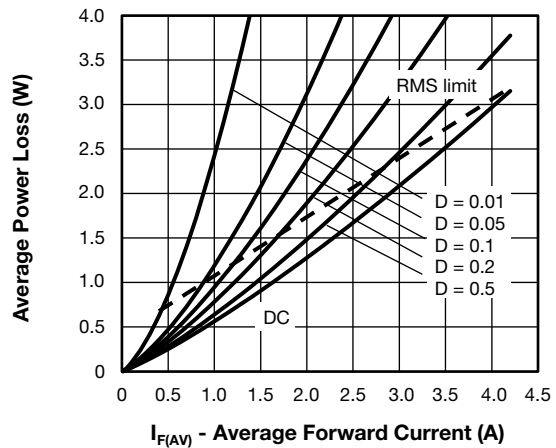


Fig. 6 - Forward Power Loss Characteristics

**Note**

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;
- $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see Fig. 6);
- $P_{dREV}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = rated  $V_R$

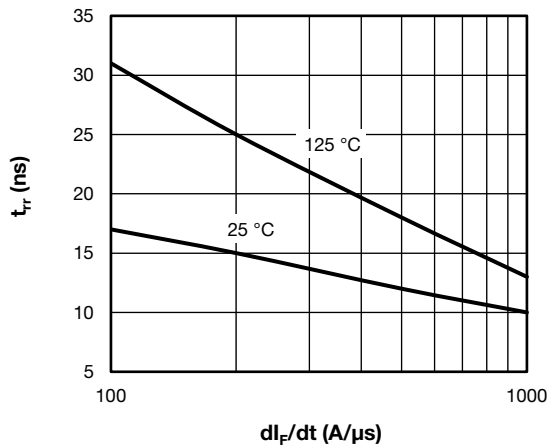


Fig. 7 - Typical Reverse Recovery vs.  $di_F/dt$

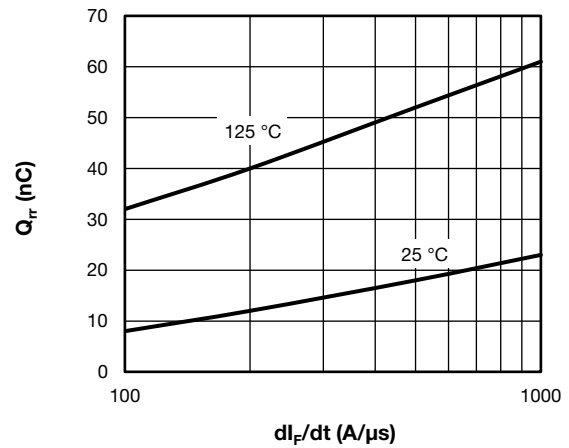


Fig. 8 - Typical Stored Charge vs.  $di_F/dt$

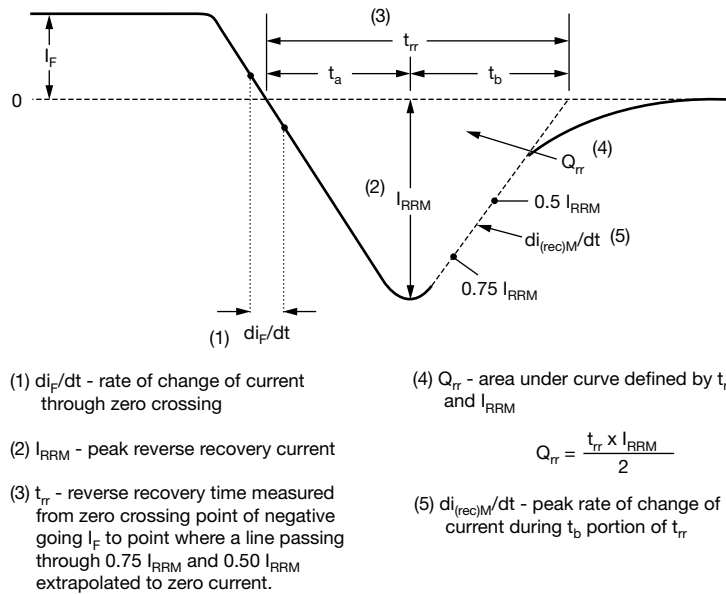
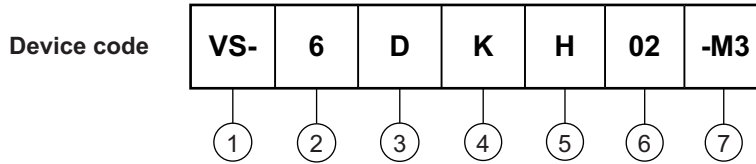


Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (6 = 6 A)
- 3** - Circuit configuration:  
D = separated cathode
- 4** - K = FlatPAK package
- 5** - Process type:  
H = hyperfast recovery
- 6** - Voltage code (02 = 200 V)
- 7** - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

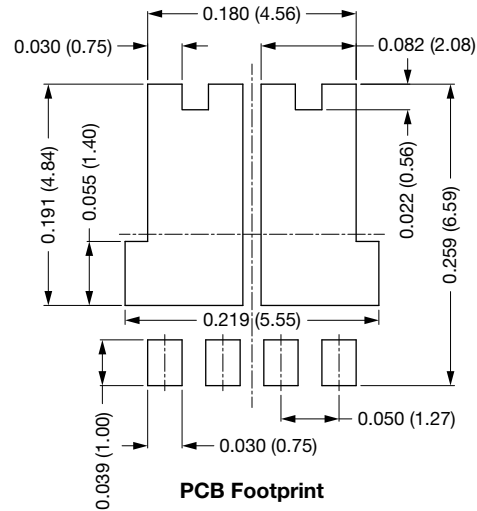
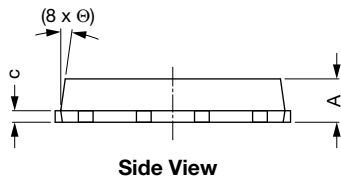
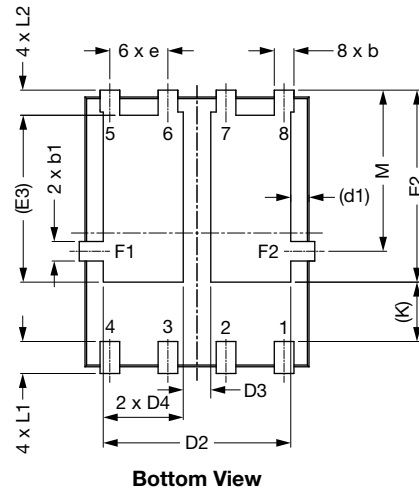
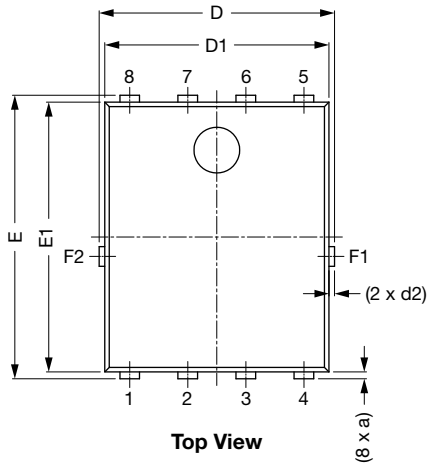
ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	PACKAGING DESCRIPTION
VS-6DKH02-M3/H	0.10	H	1500	7" diameter plastic tape and reel
VS-6DKH02-M3/I	0.10	I	6000	13" diameter plastic tape and reel

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?96056">www.vishay.com/doc?96056</a>
Part marking information	<a href="http://www.vishay.com/doc?96059">www.vishay.com/doc?96059</a>
Packaging information	<a href="http://www.vishay.com/doc?88869">www.vishay.com/doc?88869</a>
SPICE model	<a href="http://www.vishay.com/doc?96882">www.vishay.com/doc?96882</a>



### FlatPAK 5 x 6 (Dual)

**DIMENSIONS** in inches (millimeters)



DIM.	INCHES			MILLIMETERS		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.035	0.039	0.043	0.89	0.99	1.09
(a)	-	0.006	-	-	0.15	-
b	0.013	0.017	0.020	0.32	0.43	0.52
b1	0.013	0.017	0.020	0.32	0.43	0.52
c	0.008	-	0.014	0.20	-	0.35
D	0.197	0.203	0.209	5.00	5.15	5.30
D1	0.189	0.193	0.197	4.80	4.90	5.00
D2	0.154	0.161	0.169	3.90	4.10	4.30
D3	0.020	0.024	0.031	0.50	0.60	0.80
D4	0.063	0.069	0.075	1.60	1.75	1.90
(d1)	-	0.016	-	-	0.40	-
(d2)	-	0.005	-	-	0.125	-
E	0.238	0.244	0.250	6.05	6.20	6.35



DIM.	INCHES			MILLIMETERS		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
E1	0.228	0.232	0.236	5.80	5.90	6.00
E2	0.157	0.165	0.173	4.00	4.20	4.40
(E3)	-	0.144	-	-	3.65	-
e	0.050 BSC			1.27 BSC		
(K)	0.039	-	-	1.00	-	-
L1	0.019	-	0.043	0.48	-	1.10
L2	0.012	-	0.031	0.30	-	0.80
M	0.128	0.138	0.148	3.25	3.50	3.75
⊖	0°	-	10°	0°	-	10°

**Notes**

- Dimensioning and tolerancing per ASME Y14.5-2009
- Dimensions D1 and E1 do not include mold flash or gate burrs
- Dimension (XX) means reference only



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